



A Novel Embedded OTP Memory Bit Cell Based on Oxide Breakdown

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Agenda

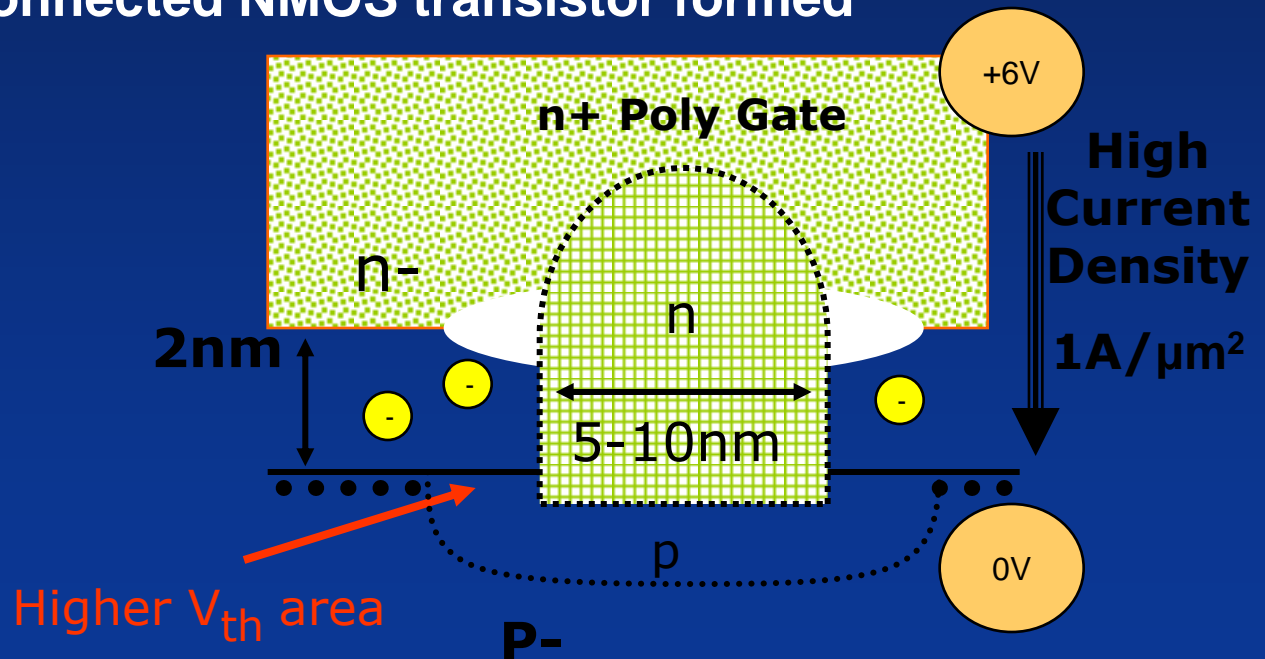
- 1T-Fuse OTP Overview
- Oxide Breakdown Mechanism
- 1T-Fuse Bit Cell
- Scaling
- Performance
- Reliability
- Security
- 1T-Fuse OTP Summary

1T-Fuse OTP Overview

- The bit cell is antifuse-based
- Programmed by predictable, irreversible gate oxide breakdown
- Basic technology around for about 20 years
- Oxide breaks down at ~5-8V
- Gate current increases up to 10,000x
- Standard logic CMOS processes
 - No additional masks or process steps

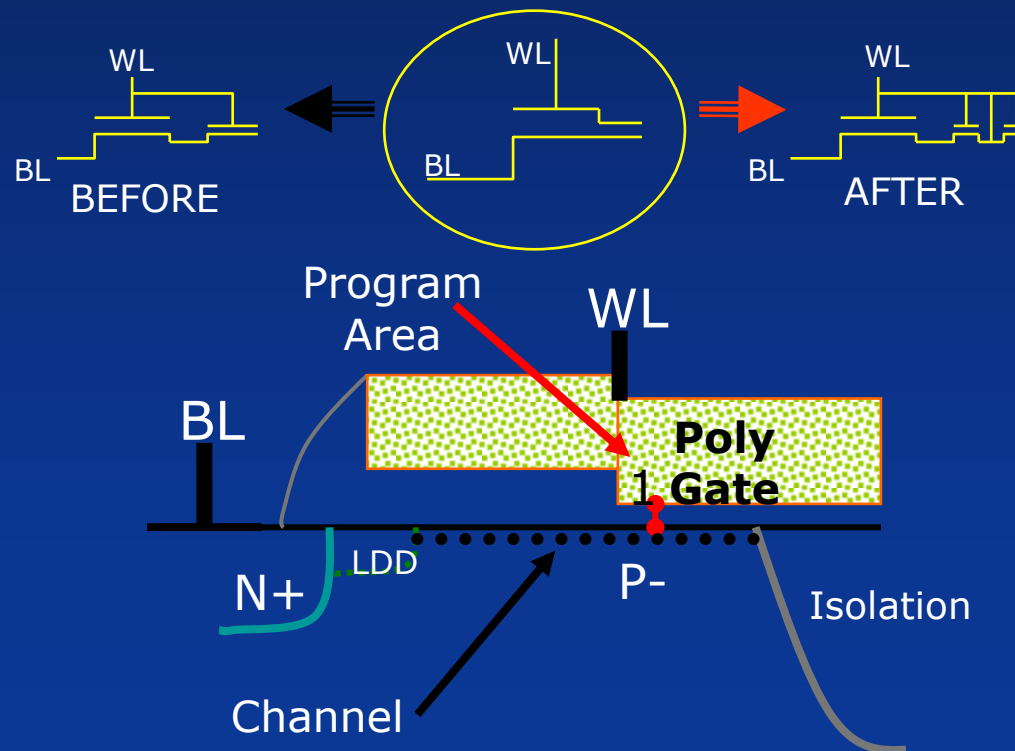
Oxide Breakdown – Nano-Scale Crystallization

- Positive gate voltage → High E field across gate
- Tunneling current → Current increases
- Oxide melts in breakdown region ($\sim 1\text{mA}/\text{mm}^2$) in $<100\text{ns}$
- Nanoscale diode-connected NMOS transistor formed



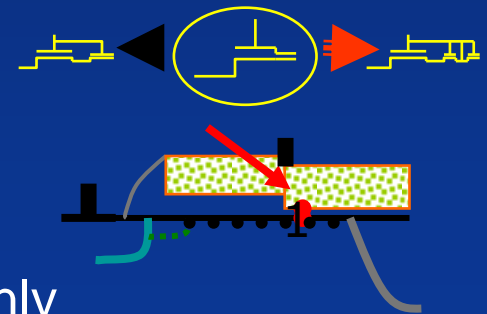
Split-Channel 1T-Fuse™ Bit Cell

- Solution: - remove LDD from breakdown area
 - 1T-Fuse breaks only in the channel area
 - → No channel tail
 - → no dependence on foundry-specific “tweaks”



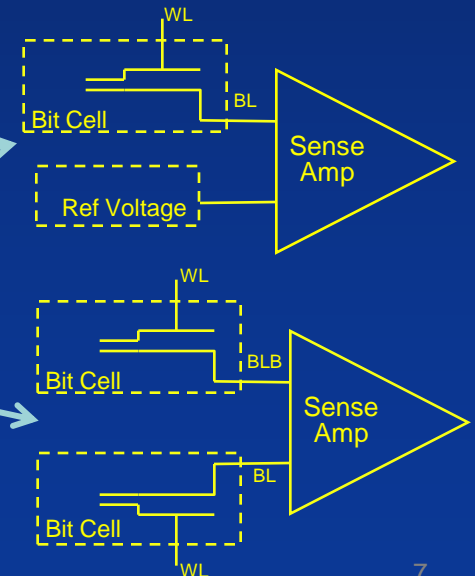
Scaling

- Typical NVM Cell Scaling Problems
 - Process node and foundry dependence
 - Minimum poly gate size
 - Additional fabrication steps
- 1T-Fuse Solution
 - No process node or foundry dependence
 - No LDD or threshold adjustments
 - No critical poly lithography
 - Predictable programming voltage
 - Function of effective oxide thickness only

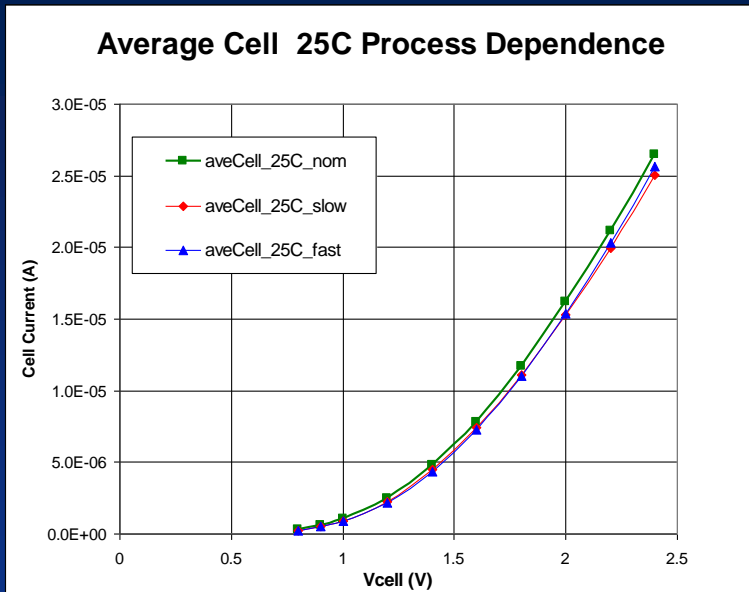


Performance

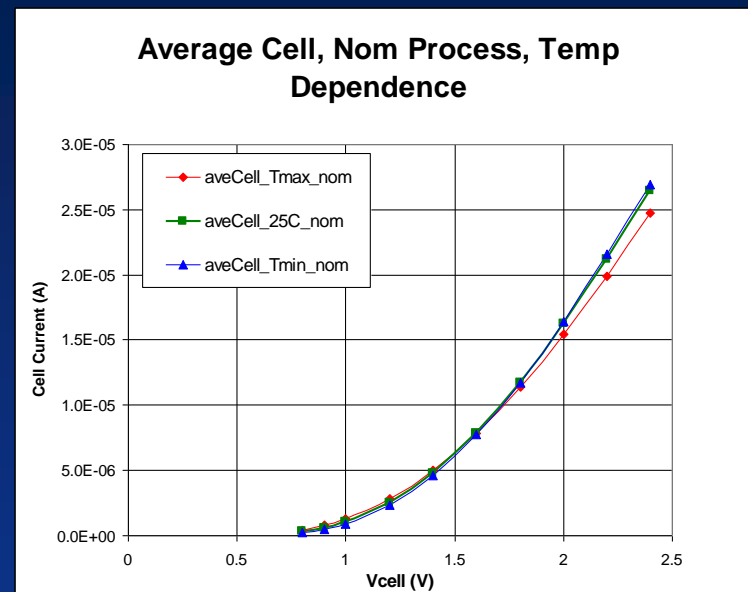
- Typical NVM Problems:
 1. Temperature Range
 2. Read Power
 3. Area
 4. Speed
 5. Voltage Range
- 1T-Fuse Solutions
 1. No Temperature sensitivity
 2. Minimal read power, no cell current flow
 3. Single-ended read = Small Area
 4. Differential = Fast Access
 5. Differential = Wide Voltage Range



Process/Temperature Sensitivity



No Fast/Slow Process Sensitivity



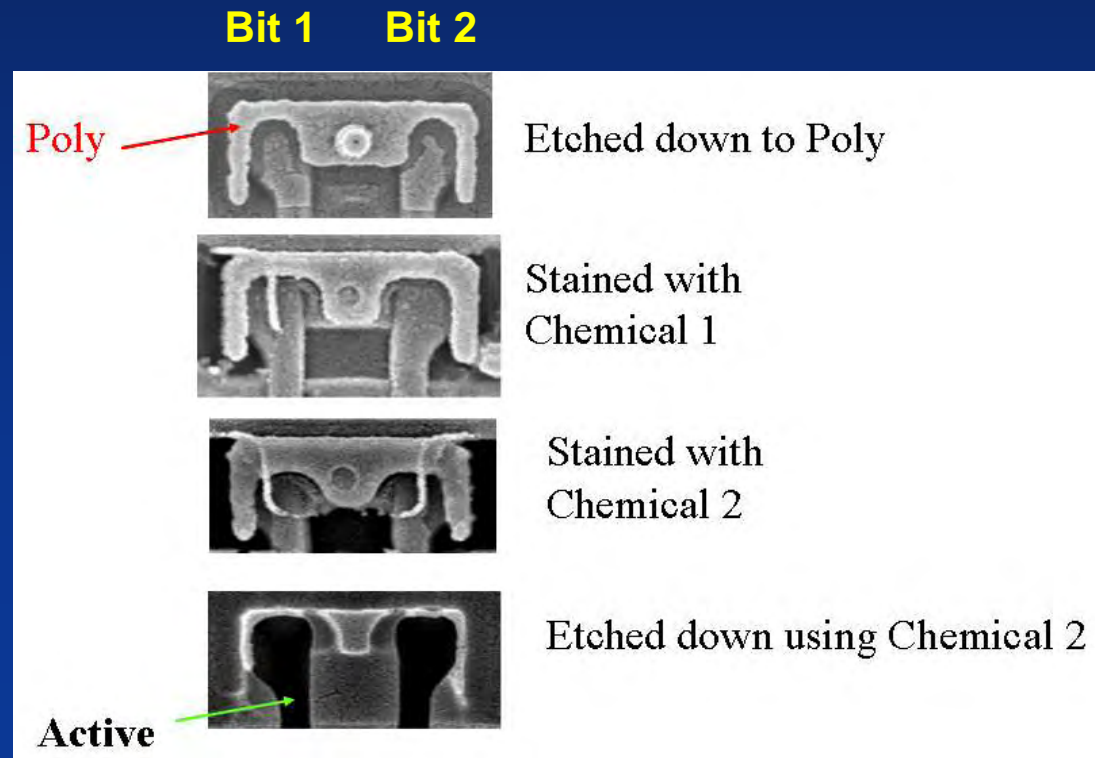
No Temperature Dependence

Reliability

- Typical NVM problem
 - Retention at High Temp
- 1T-Fuse Results
 - Multiple Foundries and Nodes
 - **125C AHTOL** – 4 ½ million Mbit-hours PASS (no failures)
 - **150C HTS** – 4 million Mbit-hours PASS (no failures)
 - **TDDB** testing used to predict retention
 - > 20 years at maximum read voltage at 125C with 50% duty cycle
 - > 100 years at 150C in differential mode

What About Bit Cell Security?

- 1T-Fuse:
 - Does not depend on charge storage
 - Extremely difficult to reverse engineer



1T-Fuse OTP Summary

- Very small, fast and reliable OTP bit cell
- Programming mechanism is irreversible oxide breakdown
- No additional masks or process steps needed
- Broad foundry and process node coverage
- Scalable to 32/28nm and below